



GP/2823

Docket No. 56386 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Wu et al.  
U.S.S.N.: 09/932,053  
FILED: August 18, 2001  
FOR: SEMICONDUCTOR PACKAGE AND FABRICATING METHOD THEREOF

GROUP: 2823

EXAMINER: H. Lee

#6/A  
Amend,  
J. McMillan  
1/8/03

CERTIFICATE OF MAILING

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to the Assistant Commissioner for Patents, Washington, DC, 20231 on November 22, 2002.

By:

Steven M. Jensen

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated August 22, 2002 of the above referenced application. Please amend the application as follows:

IN THE CLAIMS

Please amend claims 5, 6, 15, and 16 as follows:

5. (Amended) The fabricating method of claim 1, wherein the insulative material is a thermosetting or thermoplastic material selected from the group consisting of epoxy, silicone and polyimide.

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